



華泰電子股份有限公司

Orient Semiconductor Electronics ,Ltd.

(股票代號 : 2329)

2024年法人說明會
INVESTOR CONFERENCE

15 NOV ,2024

簡報大綱

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公司簡介



公司歷史



資本額 Capital : US\$ 237M(NTD7.40B)

Common Stock : US\$ 179M(NTD5.60B)

Preferred C Stock : US\$ 58M(NTD1.80B)

2024

53th Anniversary Celebration

2015 & 2020

Strategic Partnership Announcement

2014

1st 16D microSD in the world

2005

Biz Transformation into Memory Market

Apr, 1994

IPO in Taiwan Stock Exchange (TSE: 2329)

1971 Established

Founder : Dr. Eugene C. Y. Duh

Headquarters : Kaohsiung, Taiwan

公司生產據點



Headquarters (Flash Memory)
(750,000 sq. ft.)

- » 6 Production buildings in NTIP
- » Headcount : around 5,000



Facility 2
(59,223 sq. ft.)



LIC
(256,200 sq. ft.)



Facility 3
(158,638 sq. ft.)



Facility 1
(146,475 sq. ft.)



Facility 5
(190,000 sq. ft.)

公司組織

**Chairman
Tony Tung**

**President
C. J. Tu**

**Testing Group
Terry Lin**

- Memory IC Testing Service
- Logic IC Testing Service

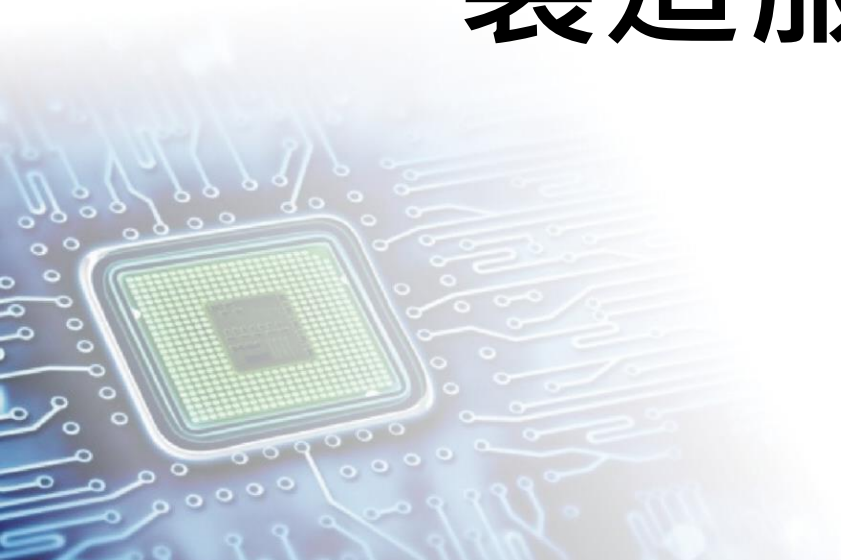
**Semiconductor Group
M. L. Tsai**

- Memory IC Packaging Service
- Logic IC Packaging Service

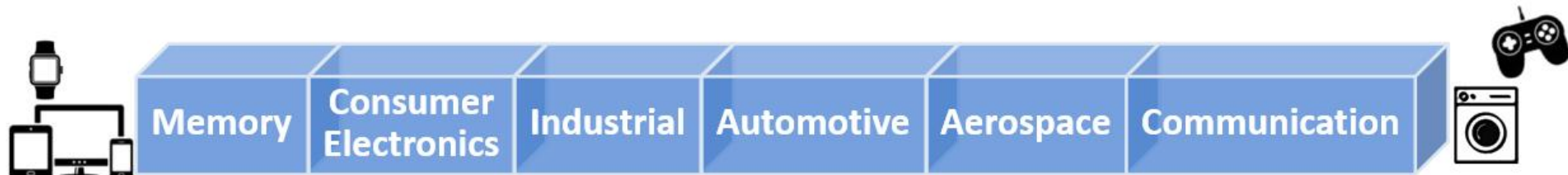
**EMS Group
Major Lee**

- EMS Service

製造服務及產品



產品及應用



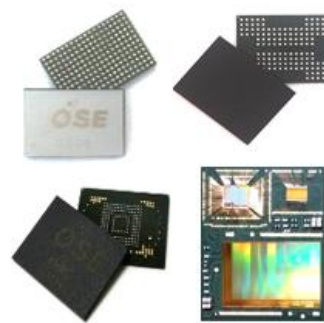
Leadframe



Flash Memory Card



CSP/SIP

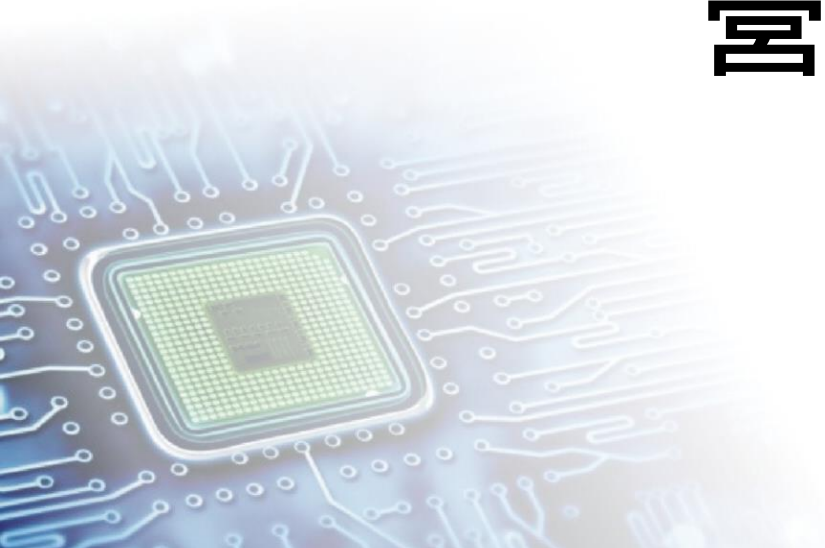


EMS



*Includes Wire Bond Type, Flip Chip Type, SiP, etc

2024 Q3 營運成果



合併綜合損益表(與上一季比較)

(單位：新台幣仟元)

	Q3/2024	%	Q2/2024	%	季變化
營業收入淨額	3,914,051	100.00%	4,060,360	100.00%	(3.60%)
營業毛利	500,548	12.79%	575,591	14.18%	(13.04%)
營業淨利(淨損)	186,906	4.78%	260,998	6.43%	(28.39%)
稅前淨利(淨損)	219,730	5.61%	410,637	10.11%	(46.49%)
所得稅利益(費用)	(42,439)	(1.08%)	(57,049)	(1.41%)	(25.61%)
非控制權益	-	-	-	-	-
歸屬於本公司業主之淨利	177,291	4.53%	353,588	8.71%	(49.86%)
基本每股盈餘(新台幣元)	0.25	-	0.50	-	-
EBITDA	449,209	11.48%	638,026	15.71%	(29.59%)

合併綜合損益表(與去年同期比較)

(單位：新台幣仟元)	Q3/2024	%	Q3/2023	%	年變化
營業收入淨額	3,914,051	100.00%	4,702,077	100.00%	(16.76%)
營業毛利	500,548	12.79%	1,063,011	22.61%	(52.91%)
營業淨利(淨損)	186,906	4.78%	708,932	15.08%	(73.64%)
稅前淨利(淨損)	219,730	5.61%	793,743	16.88%	(72.32%)
所得稅利益(費用)	(42,439)	(1.08%)	(207,042)	(4.40%)	(79.50%)
非控制權益	-	-	-	-	-
歸屬於本公司業主之淨利	177,291	4.53%	586,701	12.48%	(69.78%)
基本每股盈餘(新台幣元)	0.25	-	0.82	-	(69.51%)
EBITDA	449,209	11.48%	1,043,304	22.19%	(56.94%)

重要資產負債表項目及財務指標(與上一季比較)

(單位：新台幣仟元)

	Q3/2024	Q2/2024	季變化
現金及約當現金	4,392,800	5,372,969	(18.24%)
按攤銷後成本衡量之金融資產	-	-	-
金融資產-非流動及採用權益法之投資	1,799,522	1,768,752	1.74%
不動產、廠房及設備	6,129,265	5,797,283	5.73%
資產總計	19,231,283	20,332,900	(5.42%)
短期借款及應付短期票券	-	-	-
一年或一營業週期內到期長期負債	325,248	250,247	29.97%
長期借款	984,067	1,027,097	(4.19%)
負債總計	7,889,705	9,193,672	(14.18%)
權益總計	11,341,578	11,139,228	1.82%
當季EBITDA	449,209	638,026	(29.59%)
重要財務指標			
負債比率	41.03%	45.22%	
應收帳款週轉天數(Q3)	97 天	101 天	
存貨週轉天數(Q3)	48 天	45 天	

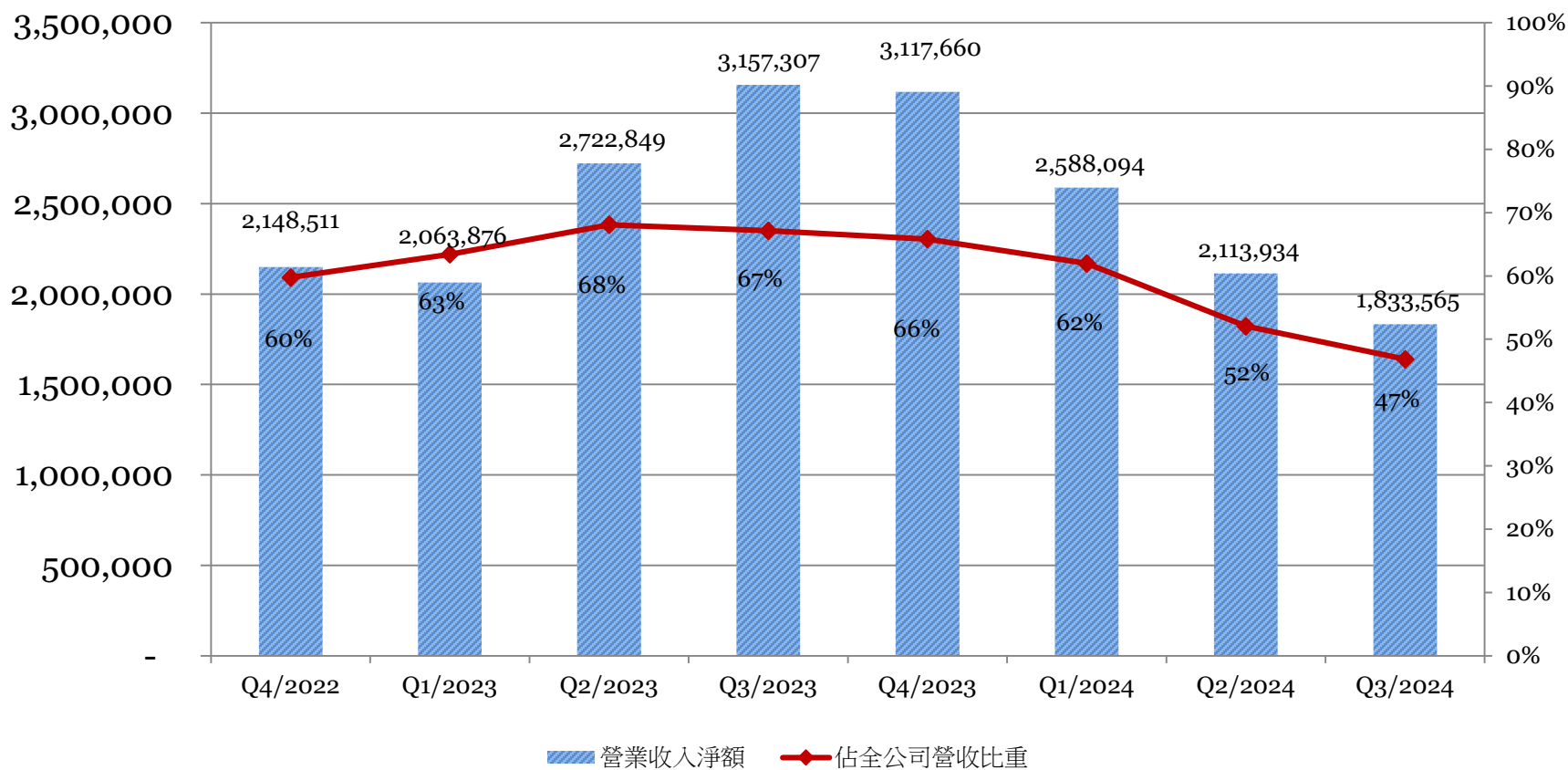
重要資產負債表項目及財務指標(與去年同期比較)

(單位：新台幣仟元)

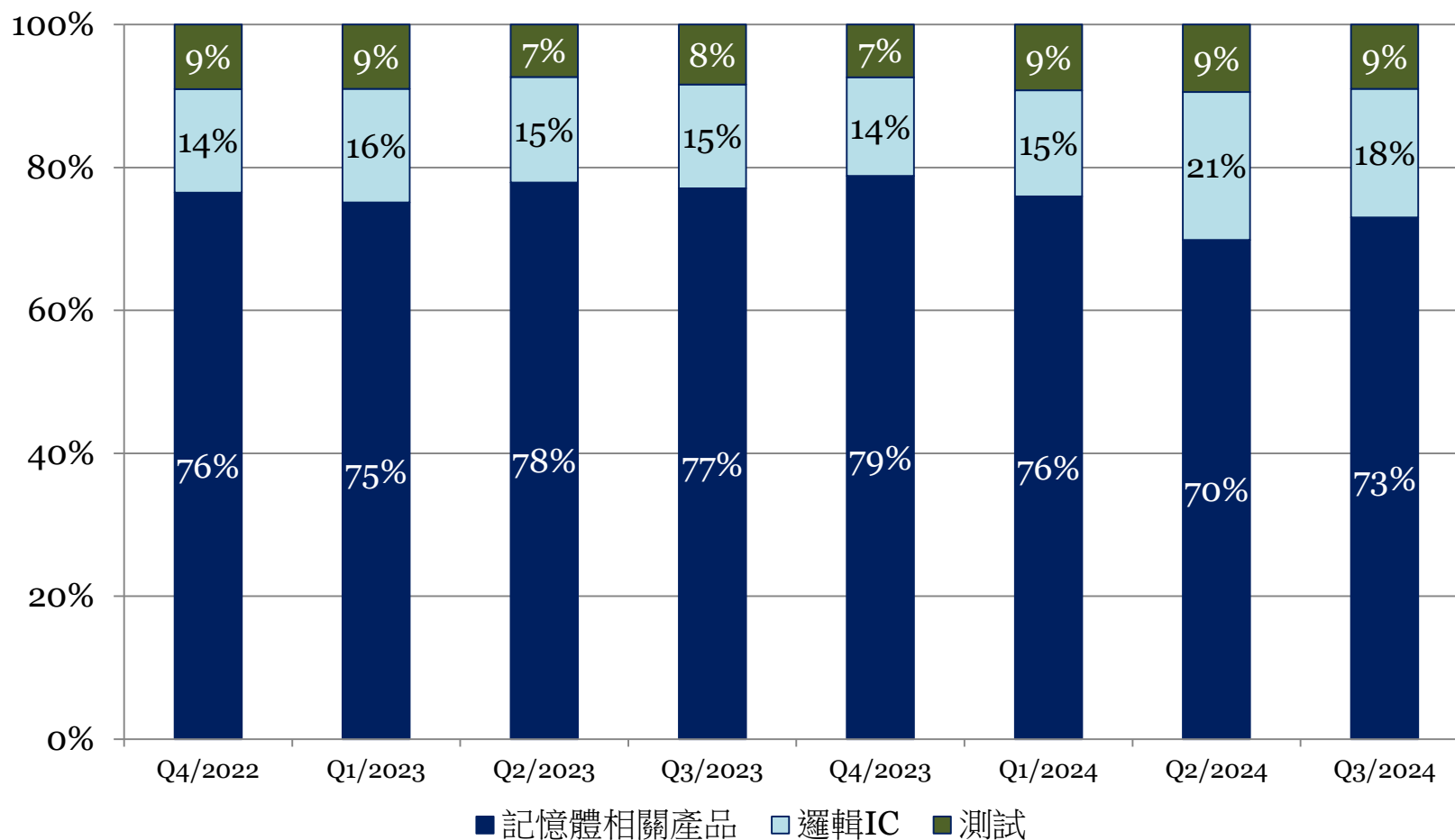
	Q3/2024	Q3/2023	年變化
現金及約當現金	4,392,800	4,056,506	8.29%
按攤銷後成本衡量之金融資產	-	-	-
金融資產-非流動及採用權益法之投資	1,799,522	1,671,283	7.67%
不動產、廠房及設備	6,129,265	5,116,203	19.80%
資產總計	19,231,283	18,455,649	4.20%
短期借款及應付短期票券	-	-	-
一年或一營業週期內到期長期負債	325,248	29,648	997.03%
長期借款	984,067	1,149,314	(14.38%)
負債總計	7,889,705	7,798,311	1.17%
權益總計	11,341,578	10,657,338	6.42%
當季EBITDA	449,209	1,043,304	(56.94%)
重要財務指標			
負債比率	41.03%	42.25%	
應收帳款週轉天數(Q1~Q3)	95 天	84 天	
存貨週轉天數(Q1~Q3)	45 天	47 天	

IC封測業務

(單位：新台幣仟元)

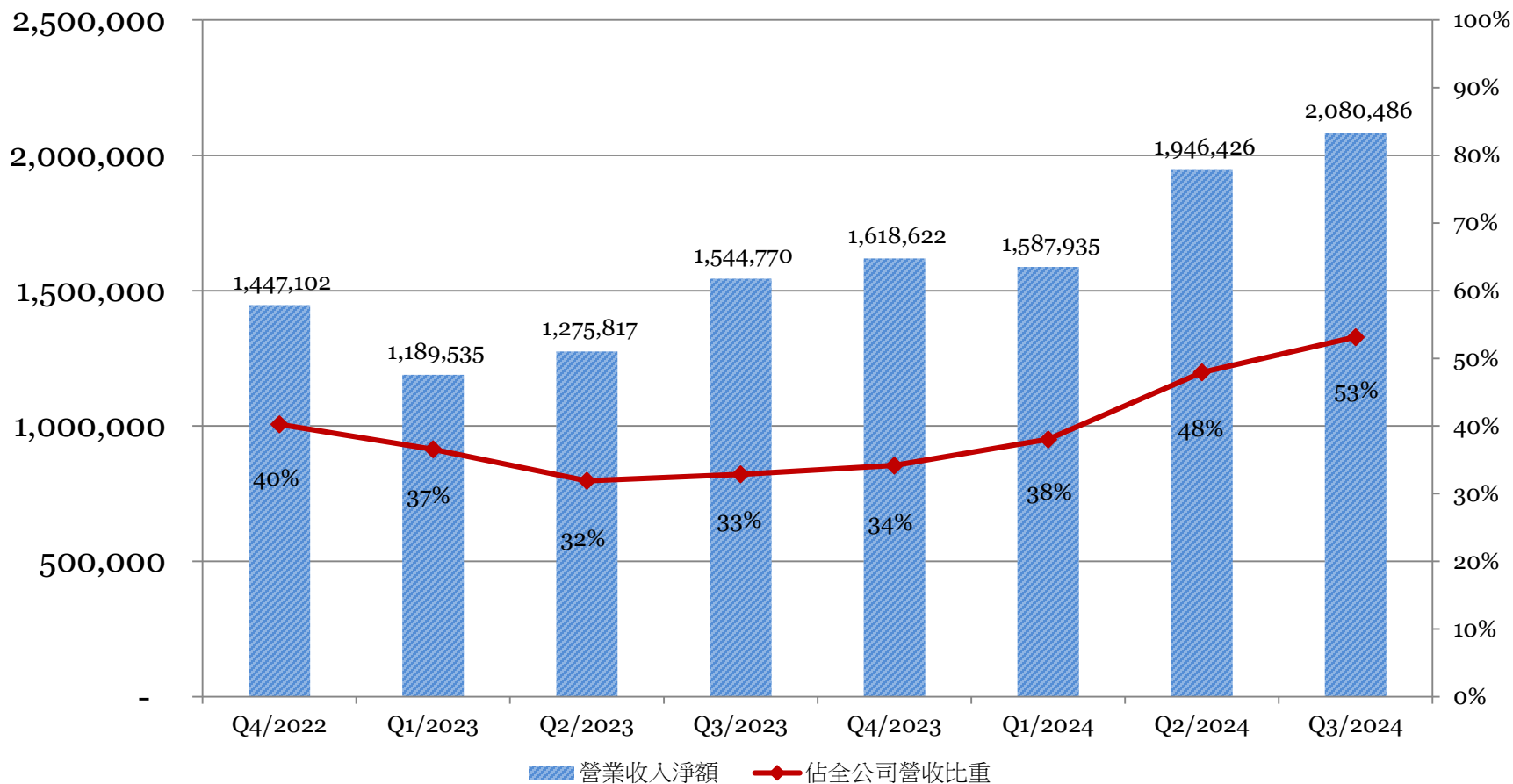


半導體封測營收-產品應用別佔比



EMS業務

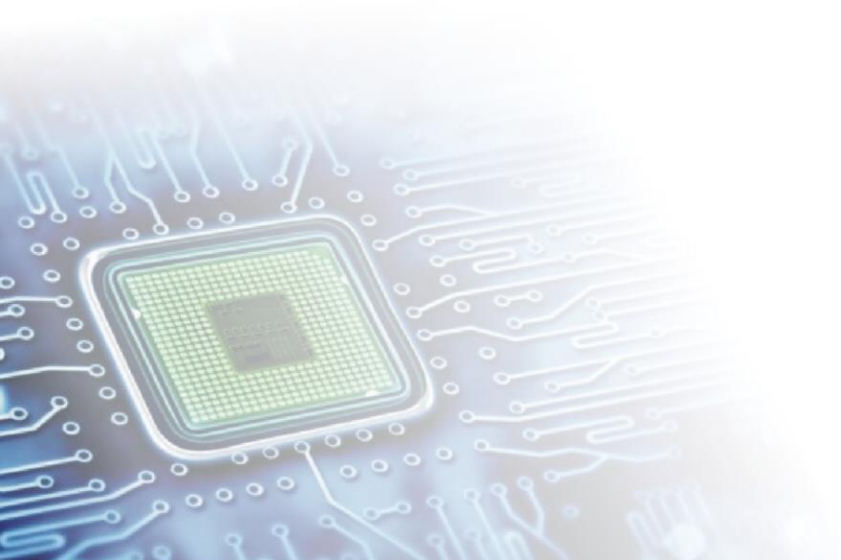
(單位：新台幣仟元)



2024 Q3 營運狀況Summary

- 半導體事業中心:
 - 終端消費性電子需求不振，客戶訂單不如預期
 - 半導體營收下降，佔全公司比重下降
 - 產能利用率偏低，固定成本造成毛利下降
 - 持續為下一波記憶體需求成長做準備
- EMS事業中心
 - 伺服器客戶帶動EMS業績成長
 - 持續為下一波記憶體需求做準備

2025 Outlook & 競爭優勢



“WHAT OSE
COULD
OFFER”

“QUALITY
SPEED
FLEXIBILITY”



- Capable of both IC & EMS / One-Stop Service.
- Sufficient experience with world-class customers working with us.



- **Advanced Process Capability**
 - 25um wafer thickness
 - 16 Layers Die Stacking for micro SD/BGA/SD
 - Sip / Flip Chip / Wire Bond / Module Availability
 - High-end Technology

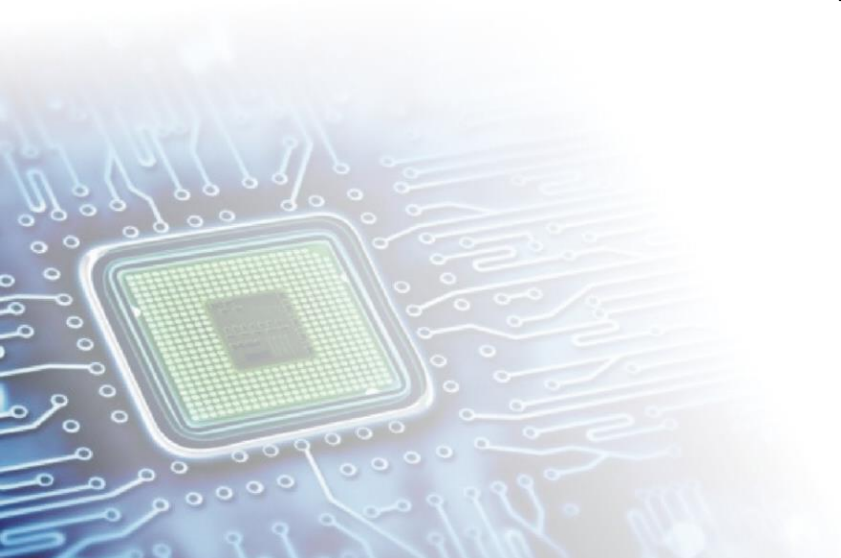


- Digitalization
- MES Automation System

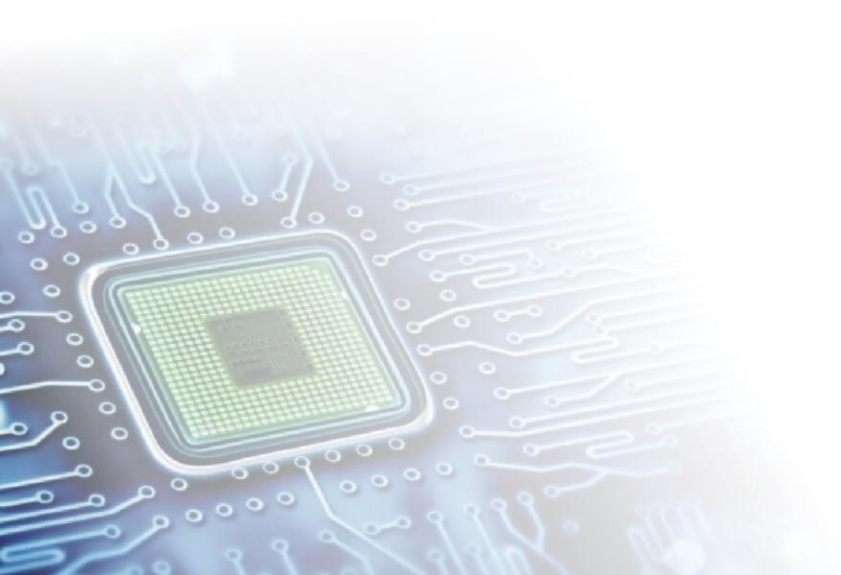


- Customer Oriented & Customization
- High Degree of Flexibility on capacity allocation

Q & A



感謝聆聽



聲明

The presentation and the relevant information mentioned in this material have been compiled from both internal and external resources.

These forward looking statements involve known and unknown risks, uncertainties and other factors, including price variation, competition, global economy, exchange rate movement and market demand, which may cause actual results to differ materially from those implied by such forward-looking statements.

The forward looking statements expressed in this material reflect the Company's current view about the future as of today. The Company is not responsible for any updates if there are any changes in the future.